

SSM3K15F

High Speed Switching Applications
Analog Switch Applications

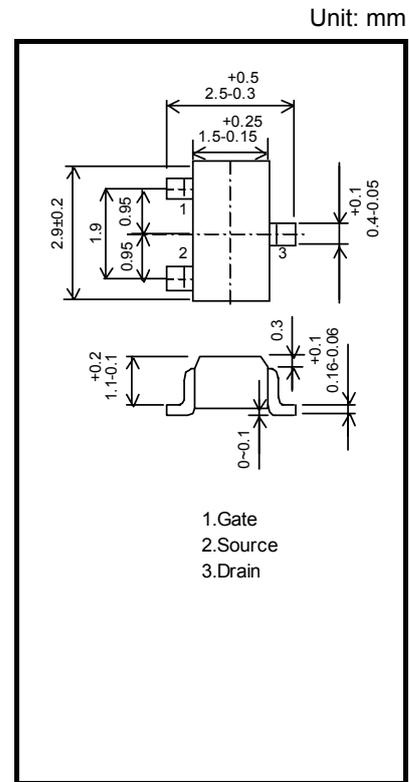
- Small package
- Low on resistance
 - : $R_{on} = 4.0 \Omega$ (max) (@ $V_{GS} = 4 V$)
 - : $R_{on} = 7.0 \Omega$ (max) (@ $V_{GS} = 2.5 V$)

Absolute Maximum Ratings (Ta = 25°C)

Characteristics	Symbol	Rating	Unit
Drain-source voltage	V_{DS}	30	V
Gate-source voltage	V_{GSS}	± 20	V
Drain current	DC	I_D	100
	Pulse	I_{DP}	200
Drain power dissipation (Ta = 25°C)	P_D	200	mW
Channel temperature	T_{ch}	150	°C
Storage temperature	T_{stg}	-55~150	°C

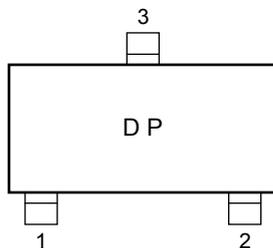
Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the TY Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

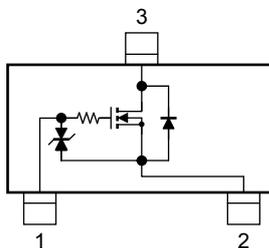


Weight: 0.012 g (typ.)

Marking



Equivalent Circuit



Handling Precaution

When handling individual devices (which are not yet mounting on a circuit board), be sure that the environment is protected against electrostatic electricity. Operators should wear anti-static clothing, and containers and other objects that come into direct contact with devices should be made of anti-static materials.

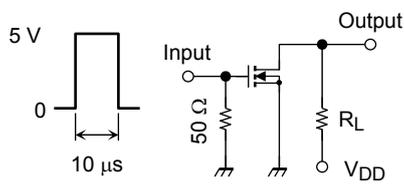
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Electrical Characteristics (Ta = 25°C)

Characteristics	Symbol	Test Condition	Min	Typ.	Max	Unit
Gate leakage current	I_{GSS}	$V_{GS} = \pm 16\text{ V}, V_{DS} = 0$	—	—	± 1	μA
Drain-source breakdown voltage	$V_{(BR)DSS}$	$I_D = 0.1\text{ mA}, V_{GS} = 0$	30	—	—	V
Drain cut-off current	I_{DSS}	$V_{DS} = 30\text{ V}, V_{GS} = 0$	—	—	1	μA
Gate threshold voltage	V_{th}	$V_{DS} = 3\text{ V}, I_D = 0.1\text{ mA}$	0.8	—	1.5	V
Forward transfer admittance	$ Y_{fs} $	$V_{DS} = 3\text{ V}, I_D = 10\text{ mA}$	25	—	—	mS
Drain-source ON resistance	$R_{DS(ON)}$	$I_D = 10\text{ mA}, V_{GS} = 4\text{ V}$	—	2.2	4.0	Ω
		$I_D = 10\text{ mA}, V_{GS} = 2.5\text{ V}$	—	4.0	7.0	
Input capacitance	C_{iss}	$V_{DS} = 3\text{ V}, V_{GS} = 0, f = 1\text{ MHz}$	—	7.8	—	pF
Reverse transfer capacitance	C_{rss}	$V_{DS} = 3\text{ V}, V_{GS} = 0, f = 1\text{ MHz}$	—	3.6	—	pF
Output capacitance	C_{oss}	$V_{DS} = 3\text{ V}, V_{GS} = 0, f = 1\text{ MHz}$	—	8.8	—	pF
Switching time	Turn-on time	$V_{DD} = 5\text{ V}, I_D = 10\text{ mA}, V_{GS} = 0\sim 5\text{ V}$	—	50	—	ns
	Turn-off time		—	180	—	

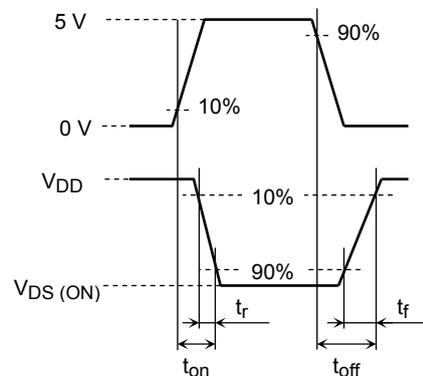
Switching Time Test Circuit

(a) Test circuit



$V_{DD} = 5\text{ V}$
 D.U. $\leq 1\%$
 Input: $t_r, t_f < 5\text{ ns}$
 ($Z_{out} = 50\ \Omega$)
 Common Source
 $T_a = 25^\circ\text{C}$

(b) V_{IN}



(c) V_{OUT}

Precaution

V_{th} can be expressed as voltage between gate and source when low operating current value is $I_D = 100\ \mu\text{A}$ for this product. For normal switching operation, $V_{GS(ON)}$ requires higher voltage than V_{th} and $V_{GS(OFF)}$ requires lower voltage than V_{th} .

(relationship can be established as follows: $V_{GS(OFF)} < V_{th} < V_{GS(ON)}$)

Please take this into consideration for using the device.